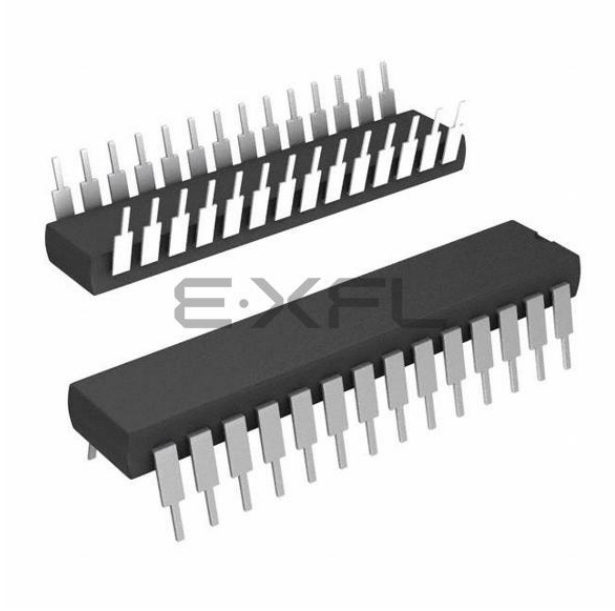

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 17x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1512-i-sp

Peripheral Highlights

- Up to 25 I/O Pins (1 input-only pin):
  - High current sink/source 25 mA/25 mA
  - Individually programmable weak pull-ups
  - Individually programmable interrupt-on-change (IOC) pins
- Timer0: 8-Bit Timer/Counter with 8-Bit Prescaler
- Enhanced Timer1:
  - 16-bit timer/counter with prescaler
  - External Gate Input mode
  - Low-power 32 kHz secondary oscillator driver
- Timer2: 8-Bit Timer/Counter with 8-Bit Period Register, Prescaler and Postscaler
- Two Capture/Compare (CCP) modules:
- Master Synchronous Serial Port (MSSP) with SPI and I^2C with:
  - 7-bit address masking
  - SMBus/PMBus™ compatibility
- Enhanced Universal Synchronous Asynchronous Receiver Transmitter (EUSART) module:
  - RS-232, RS-485 and LIN compatible
  - Auto-Baud Detect
  - Auto-wake-up on start

5.2 Clock Source Types

Clock sources can be classified as external or internal.

External clock sources rely on external circuitry for the clock source to function. Examples are: oscillator modules (EC mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (RC) mode circuits.

Internal clock sources are contained within the oscillator module. The internal oscillator block has two internal oscillators that are used to generate the internal system clock sources: the 16 MHz High-Frequency Internal Oscillator and the 31 kHz Low-Frequency Internal Oscillator (LFINTOSC).

The system clock can be selected between external or internal clock sources via the System Clock Select (SCS) bits in the OSCCON register. See **Section 5.3 "Clock Switching"** for additional information.

5.2.1 EXTERNAL CLOCK SOURCES

An external clock source can be used as the device system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in the Configuration Words to select an external clock source that will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to:
  - Secondary oscillator during run-time, or
  - An external clock source determined by the value of the FOSC bits.

See **Section 5.3 "Clock Switching"**for more information.

5.2.1.1 EC Mode

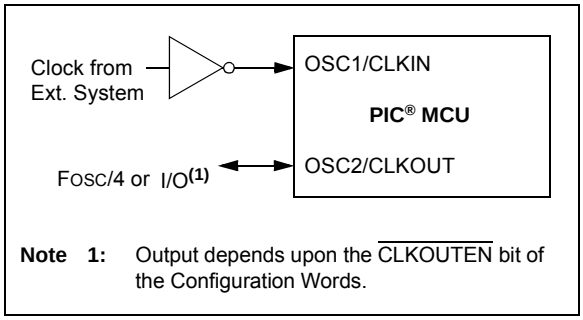
The External Clock (EC) mode allows an externally generated logic level signal to be the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. Figure 5-2 shows the pin connections for EC mode.

EC mode has three power modes to select from through Configuration Words:

- High power, 4-20 MHz (FOSC = 111)
- Medium power, 0.5-4 MHz (FOSC = 110)
- Low power, 0-0.5 MHz (FOSC = 101)

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 5-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Output depends upon the $\overline{\text{CLKOUTEN}}$ bit of the Configuration Words.

5.2.1.2 LP, XT, HS Modes

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 5-3). The three modes select a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is designed to drive only 32.768 kHz tuning-fork type crystals (watch crystals).

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

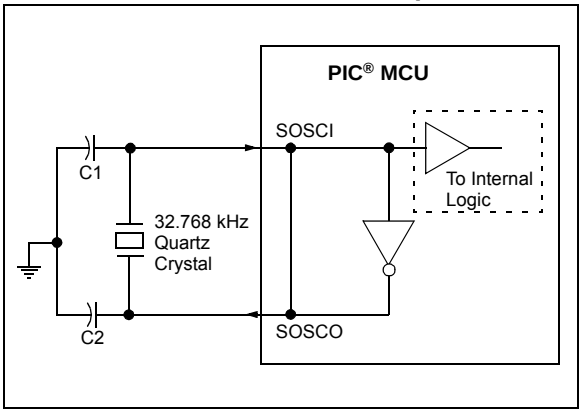
Figure 5-3 and Figure 5-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

5.2.1.4 Secondary Oscillator

The secondary oscillator is a separate crystal oscillator that is associated with the Timer1 peripheral. It is optimized for timekeeping operations with a 32.768 kHz crystal connected between the SOSCO and SOSCI device pins.

The secondary oscillator can be used as an alternate system clock source and can be selected during run-time using clock switching. Refer to **Section 5.3 "Clock Switching"** for more information.

FIGURE 5-5: QUARTZ CRYSTAL OPERATION (SECONDARY OSCILLATOR)



Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

2: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

3: For oscillator design assistance, reference the following Microchip Applications Notes:

- *AN826, Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices* (DS00826)
- *AN849, Basic PIC® Oscillator Design* (DS00849)
- *AN943, Practical PIC® Oscillator Analysis and Design* (DS00943)
- *AN949, Making Your Oscillator Work* (DS00949)
- *TB097, Interfacing a Micro Crystal MS1V-T1K 32.768 kHz Tuning Fork Crystal to a PIC16F690/SS* (DS91097)
- *AN1288, Design Practices for Low-Power External Oscillators* (DS01288)

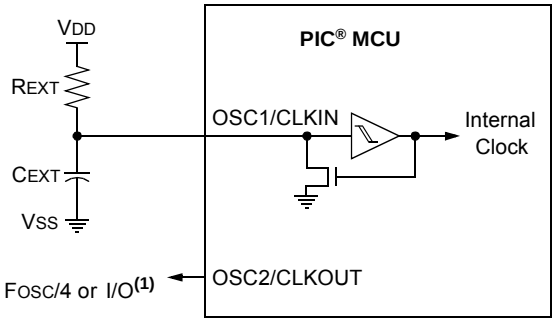
5.2.1.5 External RC Mode

The external Resistor-Capacitor (RC) modes support the use of an external RC circuit. This allows the designer maximum flexibility in frequency choice while keeping costs to a minimum when clock accuracy is not required.

The RC circuit connects to OSC1. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. The function of the OSC2/CLKOUT pin is determined by the $\overline{\text{CLKOUTEN}}$ bit in Configuration Words.

Figure 5-6 shows the external RC mode connections.

FIGURE 5-6: EXTERNAL RC MODES



Recommended values: 10 kΩ ≤ REXT ≤ 100 kΩ, <3V
3 kΩ ≤ REXT ≤ 100 kΩ, 3-5V
CEXT > 20 pF, 2-5V

Note 1: Output depends upon the $\overline{\text{CLKOUTEN}}$ bit of the Configuration Words.

The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values and the operating temperature. Other factors affecting the oscillator frequency are:

- threshold voltage variation
- component tolerances
- packaging variations in capacitance

The user also needs to take into account variation due to tolerance of the external RC components used.

10.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator. Time intervals in this chapter are based on a nominal interval of 1 ms. See **Section 25.0 "Electrical Specifications"** for the LFINTOSC tolerances.

10.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Words. See Table 10-1.

10.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Words are set to '11', the WDT is always on.

WDT protection is active during Sleep.

10.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Words are set to '10', the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

10.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Words are set to '01', the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 10-2 for more details.

TABLE 10-1: WDT OPERATING MODES

WDTE<1:0>	SWDTEN	Device Mode	WDT Mode
11	X	X	Active
10	X	Awake	Active
		Sleep	Disabled
01	1	X	Active
	0		Disabled
00	X	X	Disabled

10.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds (nominal). After a Reset, the default time-out period is two seconds.

10.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- CLRWDT instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail
- WDT is disabled
- Oscillator Start-up Timer (OST) is running

See Table 10-2 for more information.

10.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting.

When the device exits Sleep, the WDT is cleared again. The WDT remains clear until the OST, if enabled, completes. See **Section 5.0 "Oscillator Module (With Fail-Safe Clock Monitor)"** for more information on the OST.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the event. See **Section 3.0 "Memory Organization"** and The STATUS register (Register 3-1) for more information.

TABLE 10-2: WDT CLEARING CONDITIONS

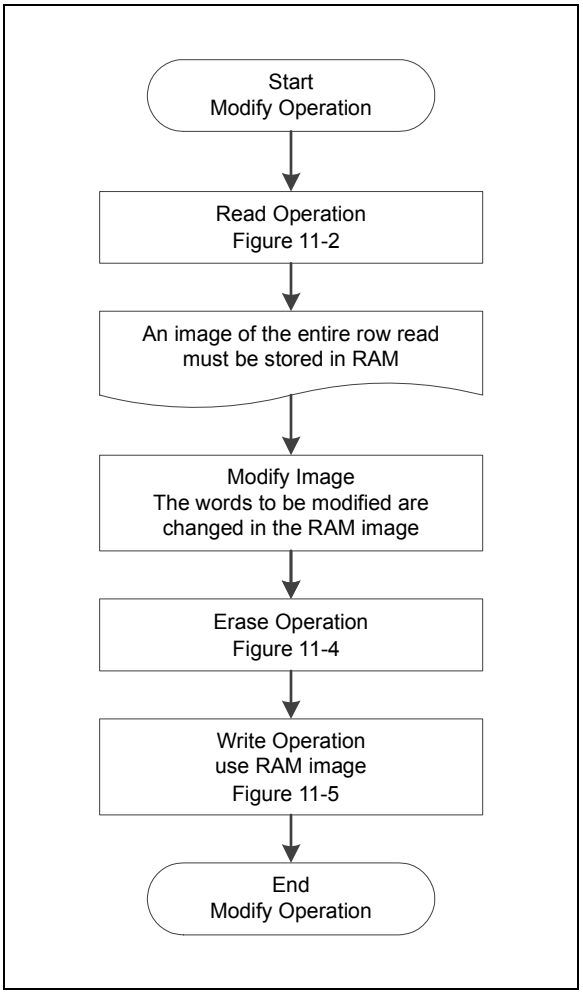
Conditions	WDT
WDTE<1:0> = 00	Cleared
WDTE<1:0> = 01 and SWDTEN = 0	
WDTE<1:0> = 10 and enter Sleep	
CLRWDT Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = SOSC, EXTRC, INTOSC, EXTCLK	
Exit Sleep + System Clock = XT, HS, LP	Cleared until the end of OST
Change INTOSC divider (IRCF bits)	Unaffected

11.3 Modifying Flash Program Memory

When modifying existing data in a program memory row, and data within that row must be preserved, it must first be read and saved in a RAM image. Program memory is modified using the following steps:

1. Load the starting address of the row to be modified.
2. Read the existing data from the row into a RAM image.
3. Modify the RAM image to contain the new data to be written into program memory.
4. Load the starting address of the row to be rewritten.
5. Erase the program memory row.
6. Load the write latches with data from the RAM image.
7. Initiate a programming operation.

FIGURE 11-7: FLASH PROGRAM MEMORY MODIFY FLOWCHART



13.0 INTERRUPT-ON-CHANGE

The PORTB pins can be configured to operate as Interrupt-On-Change (IOC) pins. An interrupt can be generated by detecting a signal that has either a rising edge or a falling edge. Any individual PORTB pin, or combination of PORTB pins, can be configured to generate an interrupt. The interrupt-on-change module has the following features:

- Interrupt-on-Change enable (Master Switch)
- Individual pin configuration
- Rising and falling edge detection
- Individual pin interrupt flags

Figure 13-1 is a block diagram of the IOC module.

13.1 Enabling the Module

To allow individual PORTB pins to generate an interrupt, the IOCIE bit of the INTCON register must be set. If the IOCIE bit is disabled, the edge detection on the pin will still occur, but an interrupt will not be generated.

13.2 Individual Pin Configuration

For each PORTB pin, a rising edge detector and a falling edge detector are present. To enable a pin to detect a rising edge, the associated IOCBPx bit of the IOCBP register is set. To enable a pin to detect a falling edge, the associated IOCBNx bit of the IOCBN register is set.

A pin can be configured to detect rising and falling edges simultaneously by setting both the IOCBPx bit and the IOCBNx bit of the IOCBP and IOCBN registers, respectively.

13.3 Interrupt Flags

The IOCBFx bits located in the IOCBF register are status flags that correspond to the interrupt-on-change pins of PORTB. If an expected edge is detected on an appropriately enabled pin, then the status flag for that pin will be set, and an interrupt will be generated if the IOCIE bit is set. The IOCIF bit of the INTCON register reflects the status of all IOCBFx bits.

13.4 Clearing Interrupt Flags

The individual status flags, (IOCBFx bits), can be cleared by resetting them to zero. If another edge is detected during this clearing operation, the associated status flag will be set at the end of the sequence, regardless of the value actually being written.

In order to ensure that no detected edge is lost while clearing flags, only AND operations masking out known changed bits should be performed. The following sequence is an example of what should be performed.

EXAMPLE 13-1: CLEARING INTERRUPT FLAGS (PORTA EXAMPLE)

```
MOVLW  0xff
XORWF  IOCAF, W
ANDWF  IOCAF, F
```

13.5 Operation in Sleep

The interrupt-on-change interrupt sequence will wake the device from Sleep mode, if the IOCIE bit is set.

If an edge is detected while in Sleep mode, the IOCBF register will be updated prior to the first instruction executed out of Sleep.

TABLE 16-1: ADC CLOCK PERIOD (TAD) VS. DEVICE OPERATING FREQUENCIES (CONTINUED)

ADC Clock Period (TAD)		Device Frequency (FOSC)				
ADC Clock Source	ADCS<2:0>	20 MHz	16 MHz	8 MHz	4 MHz	1 MHz
Fosc/16	101	800 ns	1.0 μs	2.0 μs	4.0 μs	16.0 μs(3)
Fosc/32	010	1.6 μs	2.0 μs	4.0 μs	8.0 μs(3)	32.0 μs(3)
Fosc/64	110	3.2 μs	4.0 μs	8.0 μs(3)	16.0 μs(3)	64.0 μs(3)
FRC	x11	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)	1.0-6.0 μs(1,4)

Legend: Shaded cells are outside of recommended range.

Note 1: The FRC source has a typical TAD time of 1.6 μs for VDD.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: The ADC clock period (TAD) and total ADC conversion time can be minimized when the ADC clock is derived from the system clock FOSC. However, the FRC clock source must be used when conversions are to be performed with the device in Sleep mode.

FIGURE 16-2: ANALOG-TO-DIGITAL CONVERSION TAD CYCLES

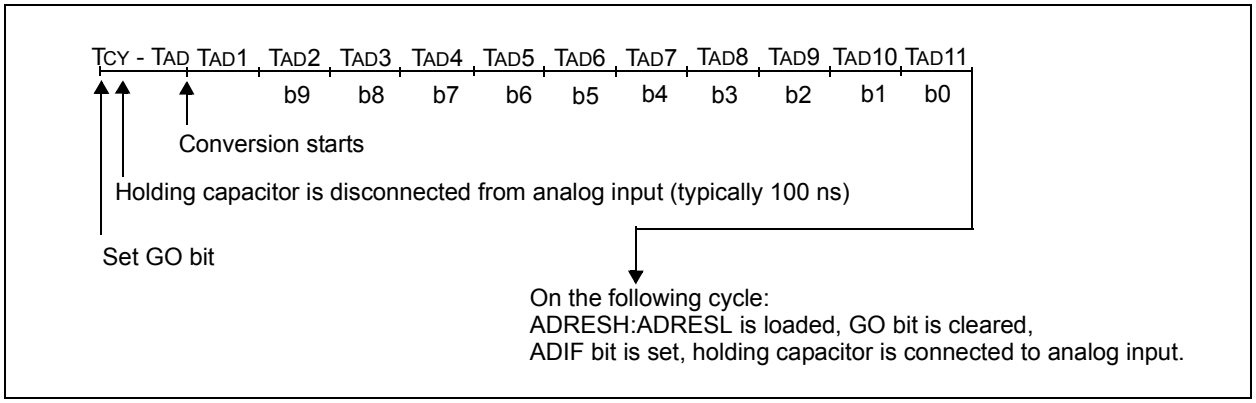


TABLE 16-3: SUMMARY OF REGISTERS ASSOCIATED WITH ADC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ADCON0	—	CHS<4:0>					GO/$\overline{\text{DONE}}$	ADON	130
ADCON1	ADFM	ADCS<2:0>			—	—	ADPREF<1:0>		131
ADRES0H	A/D Result Register High								132, 133
ADRES0L	A/D Result Register Low								132, 133
ANSELA	—	—	ANSA5	—	ANSA3	ANSA2	ANSA1	ANSA0	104
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	108
ANSELC	ANSC7	ANSC6	ANSC5	ANSC4	ANSC3	ANSC2	—	—	111
CCP1CON	—	—	DC1B<1:0>		CCP1M<3:0>				236
CCP2CON	—	—	DC2B<1:0>		CCP2M<3:0>				236
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	—	—	ADFVR<1:0>		120
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	69
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	70
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	72
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	103
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	107
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	110

Legend: — = unimplemented read as '0'. Shaded cells are not used for ADC module.

FIGURE 18-3: TIMER1 GATE ENABLE MODE

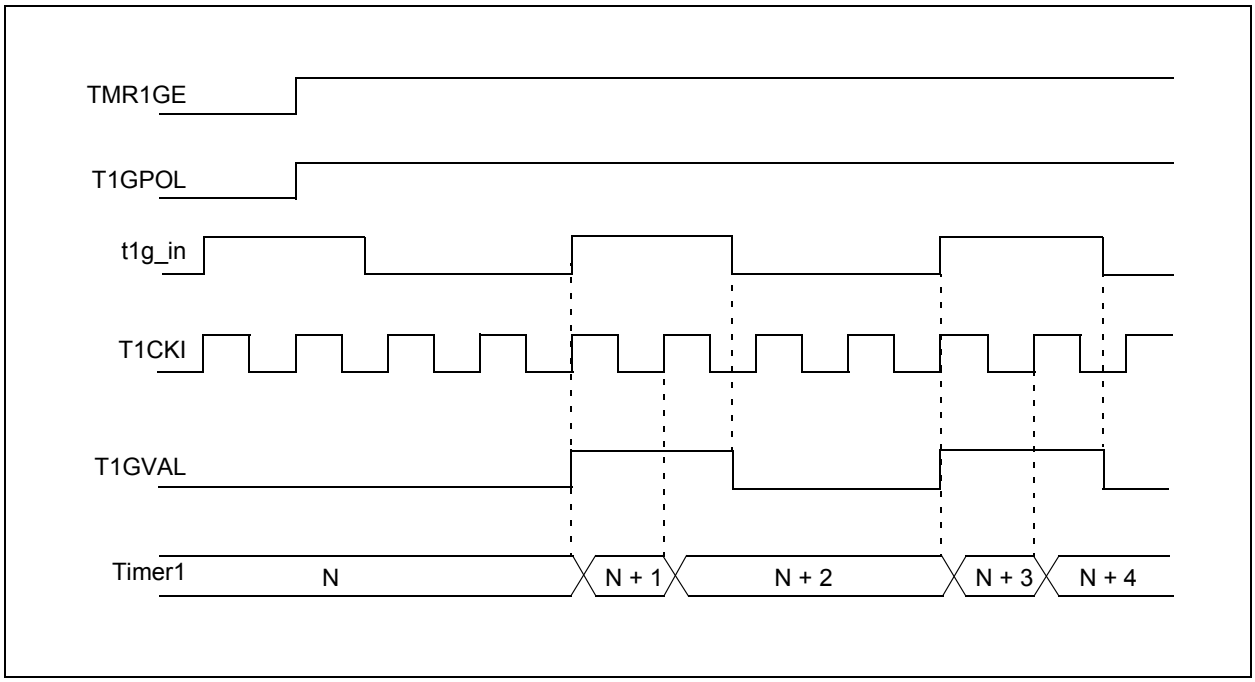
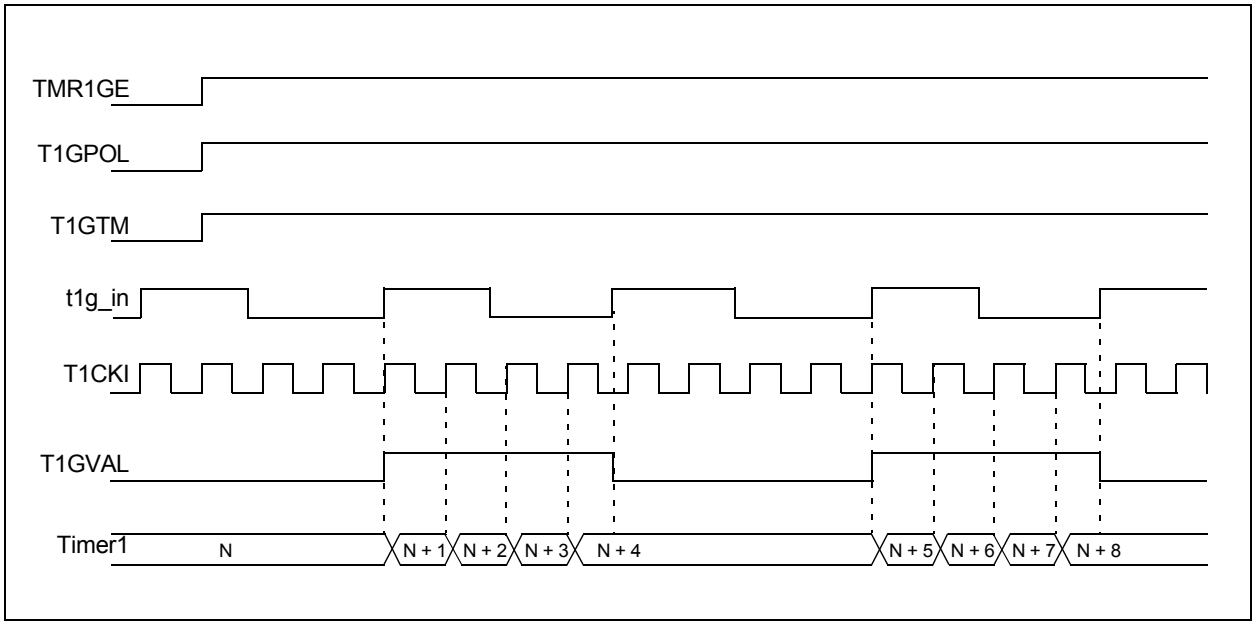


FIGURE 18-4: TIMER1 GATE TOGGLE MODE



20.4.5 START CONDITION

The I^2C specification defines a Start condition as a transition of SDA from a high to a low state while SCL line is high. A Start condition is always generated by the master and signifies the transition of the bus from an Idle to an Active state. Figure 20-12 shows wave forms for Start and Stop conditions.

A bus collision can occur on a Start condition if the module samples the SDA line low before asserting it low. This does not conform to the I^2C Specification that states no bus collision can occur on a Start.

20.4.6 STOP CONDITION

A Stop condition is a transition of the SDA line from low-to-high state while the SCL line is high.

Note: At least one SCL low time must appear before a Stop is valid, therefore, if the SDA line goes low then high again while the SCL line stays high, only the Start condition is detected.

20.4.7 RESTART CONDITION

A Restart is valid any time that a Stop would be valid. A master can issue a Restart if it wishes to hold the bus after terminating the current transfer. A Restart has the same effect on the slave that a Start would, resetting all slave logic and preparing it to clock in an address. The master may want to address the same or another slave.

In 10-bit Addressing Slave mode a Restart is required for the master to clock data out of the addressed slave. Once a slave has been fully addressed, matching both high and low address bytes, the master can issue a Restart and the high address byte with the R/$\overline{W}$ bit set. The slave logic will then hold the clock and prepare to clock out data.

After a full match with R/$\overline{W}$ clear in 10-bit mode, a prior match flag is set and maintained. Until a Stop condition, a high address with R/$\overline{W}$ clear, or high address match fails.

20.4.8 START/STOP CONDITION INTERRUPT MASKING

The SCIE and PCIE bits of the SSPCON3 register can enable the generation of an interrupt in Slave modes that do not typically support this function. Slave modes where interrupt on Start and Stop detect are already enabled, these bits will have no effect.

FIGURE 20-12: I^2C START AND STOP CONDITIONS

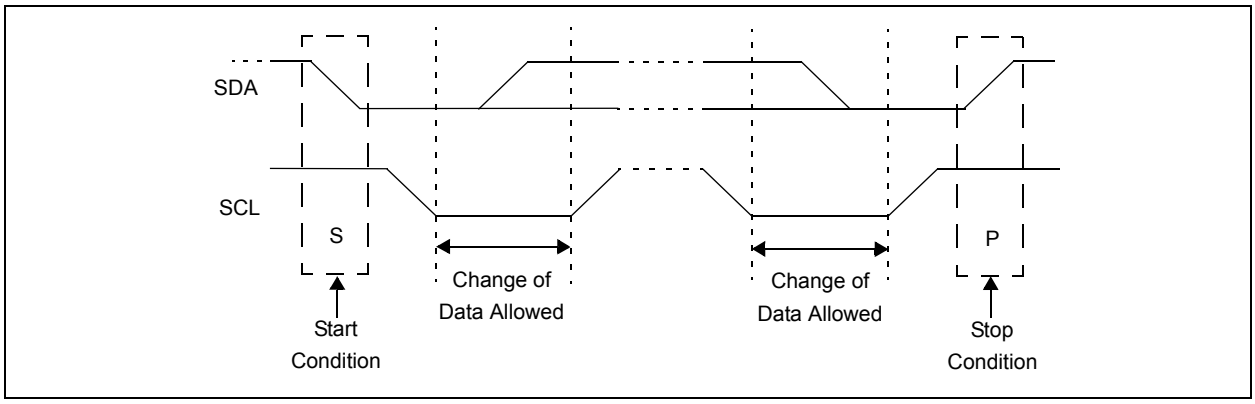
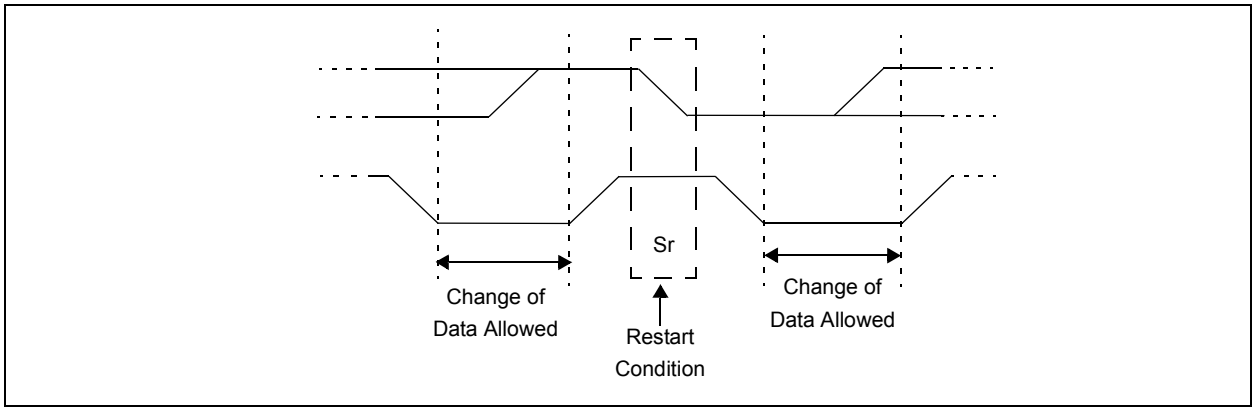


FIGURE 20-13: I^2C RESTART CONDITION



20.6.7 I²C MASTER MODE RECEPTION

Master mode reception is enabled by programming the Receive Enable bit, RCEN bit of the SSPCON2 register.

Note:	The MSSP module must be in an Idle state before the RCEN bit is set or the RCEN bit will be disregarded.

The Baud Rate Generator begins counting and on each rollover, the state of the SCL pin changes (high-to-low/low-to-high) and data is shifted into the SSPSR. After the falling edge of the eighth clock, the receive enable flag is automatically cleared, the contents of the SSPSR are loaded into the SSPBUF, the BF flag bit is set, the SSPIF flag bit is set and the Baud Rate Generator is suspended from counting, holding SCL low. The MSSP is now in Idle state awaiting the next command. When the buffer is read by the CPU, the BF flag bit is automatically cleared. The user can then send an Acknowledge bit at the end of reception by setting the Acknowledge Sequence Enable, ACKEN bit of the SSPCON2 register.

20.6.7.1 BF Status Flag

In receive operation, the BF bit is set when an address or data byte is loaded into SSPBUF from SSPSR. It is cleared when the SSPBUF register is read.

20.6.7.2 SSPOV Status Flag

In receive operation, the SSPOV bit is set when eight bits are received into the SSPSR and the BF flag bit is already set from a previous reception.

20.6.7.3 WCOL Status Flag

If the user writes the SSPBUF when a receive is already in progress (i.e., SSPSR is still shifting in a data byte), the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

20.6.7.4 Typical Receive Sequence:

1. The user generates a Start condition by setting the SEN bit of the SSPCON2 register.
2. SSPIF is set by hardware on completion of the Start.
3. SSPIF is cleared by software.
4. User writes SSPBUF with the slave address to transmit and the R/$\overline{W}$ bit set.
5. Address is shifted out the SDA pin until all eight bits are transmitted. Transmission begins as soon as SSPBUF is written to.
6. The MSSP module shifts in the $\overline{ACK}$ bit from the slave device and writes its value into the ACKSTAT bit of the SSPCON2 register.
7. The MSSP module generates an interrupt at the end of the ninth clock cycle by setting the SSPIF bit.
8. User sets the RCEN bit of the SSPCON2 register and the master clocks in a byte from the slave.
9. After the 8th falling edge of SCL, SSPIF and BF are set.
10. Master clears SSPIF and reads the received byte from SSPUF, clears BF.
11. Master sets $\overline{ACK}$ value sent to slave in ACKDT bit of the SSPCON2 register and initiates the $\overline{ACK}$ by setting the ACKEN bit.
12. Masters $\overline{ACK}$ is clocked out to the slave and SSPIF is set.
13. User clears SSPIF.
14. Steps 8-13 are repeated for each received byte from the slave.
15. Master sends a not $\overline{ACK}$ or Stop to end communication.

20.7 BAUD RATE GENERATOR

The MSSP module has a Baud Rate Generator available for clock generation in both I^2C and SPI Master modes. The Baud Rate Generator (BRG) reload value is placed in the SSPADD register (Register 20-7). When a write occurs to SSPBUF, the Baud Rate Generator will automatically begin counting down.

Once the given operation is complete, the internal clock will automatically stop counting and the clock pin will remain in its last state.

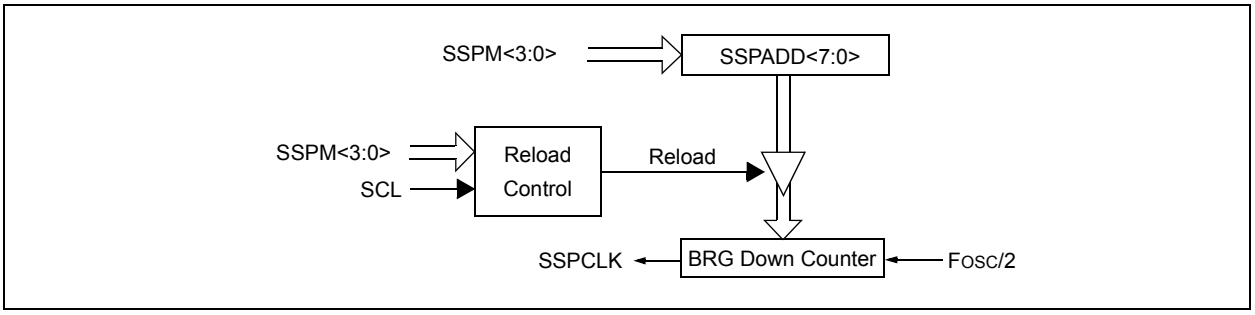
An internal signal "Reload" in Figure 20-39 triggers the value from SSPADD to be loaded into the BRG counter. This occurs twice for each oscillation of the module clock line. The logic dictating when the reload signal is asserted depends on the mode the MSSP is being operated in.

Table 20-1 demonstrates clock rates based on instruction cycles and the BRG value loaded into SSPADD.

EQUATION 20-1: BRG CLOCK FREQUENCY

$$F_{CLOCK} = \frac{F_{OSC}}{(SSPADD + 1)(4)}$$

FIGURE 20-40: BAUD RATE GENERATOR BLOCK DIAGRAM



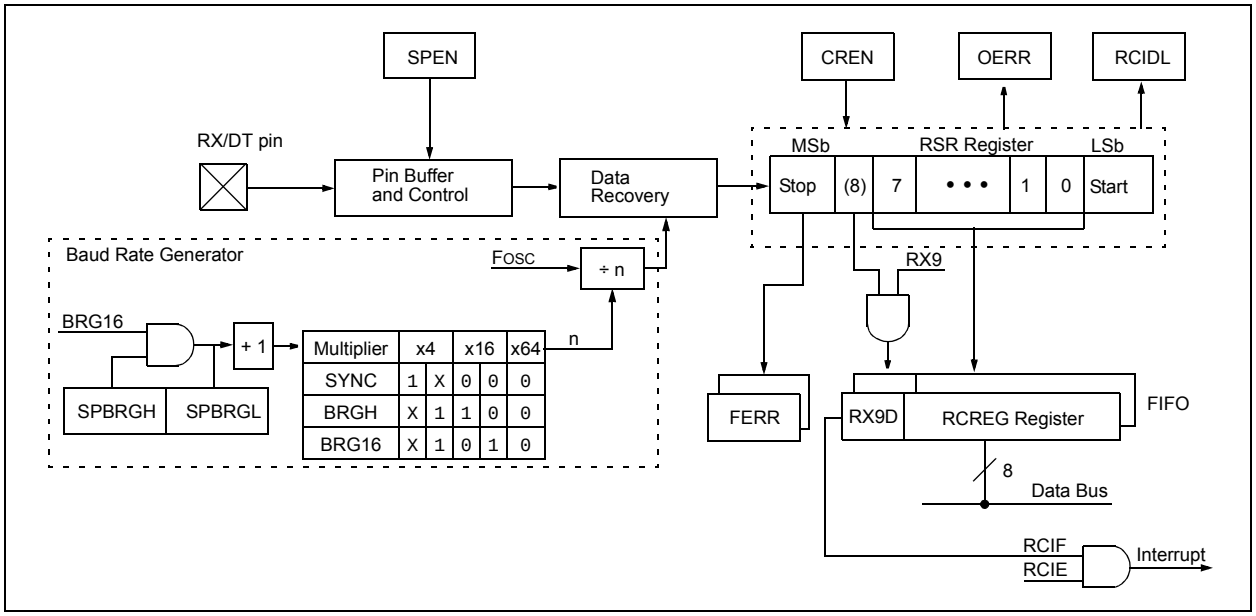
Note: Values of 0x00, 0x01 and 0x02 are not valid for SSPADD when used as a Baud Rate Generator for I^2C. This is an implementation limitation.

TABLE 20-1: MSSP CLOCK RATE W/BRG

FOSC	FCY	BRG Value	FCLOCK (2 Rollovers of BRG)
16 MHz	4 MHz	09h	400 kHz(1)
16 MHz	4 MHz	0Ch	308 kHz
16 MHz	4 MHz	27h	100 kHz
4 MHz	1 MHz	09h	100 kHz

Note 1: The I^2C interface does not conform to the 400 kHz I^2C specification (which applies to rates greater than 100 kHz) in all details, but may be used with care where higher rates are required by the application.

FIGURE 22-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 22-1, Register 22-2 and Register 22-3, respectively.

When the receiver or transmitter section is not enabled then the corresponding RX or TX pin may be used for general purpose input and output.

22.4.4 BREAK CHARACTER SEQUENCE

The EUSART module has the capability of sending the special Break character sequences that are required by the LIN bus standard. A Break character consists of a Start bit, followed by 12 '0' bits and a Stop bit.

To send a Break character, set the SENDB and TXEN bits of the TXSTA register. The Break character transmission is then initiated by a write to the TXREG. The value of data written to TXREG will be ignored and all '0's will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

The TRMT bit of the TXSTA register indicates when the transmit operation is active or idle, just as it does during normal transmission. See Figure 22-9 for the timing of the Break character sequence.

22.4.4.1 Break and Sync Transmit Sequence

The following sequence will start a message frame header made up of a Break, followed by an auto-baud Sync byte. This sequence is typical of a LIN bus master.

1. Configure the EUSART for the desired mode.
2. Set the TXEN and SENDB bits to enable the Break sequence.
3. Load the TXREG with a dummy character to initiate transmission (the value is ignored).
4. Write '55h' to TXREG to load the Sync character into the transmit FIFO buffer.
5. After the Break has been sent, the SENDB bit is reset by hardware and the Sync character is then transmitted.

When the TXREG becomes empty, as indicated by the TXIF, the next data byte can be written to TXREG.

22.4.5 RECEIVING A BREAK CHARACTER

The Enhanced EUSART module can receive a Break character in two ways.

The first method to detect a Break character uses the FERR bit of the RCSTA register and the Received data as indicated by RCREG. The Baud Rate Generator is assumed to have been initialized to the expected baud rate.

A Break character has been received when;

- RCIF bit is set
- FERR bit is set
- RCREG = 00h

The second method uses the Auto-Wake-up feature described in **Section 22.4.3 "Auto-Wake-up on Break"**. By enabling this feature, the EUSART will sample the next two transitions on RX/DT, cause an RCIF interrupt, and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Detect feature. For both methods, the user can set the ABDEN bit of the BAUDCON register before placing the EUSART in Sleep mode.

FIGURE 22-9: SEND BREAK CHARACTER SEQUENCE

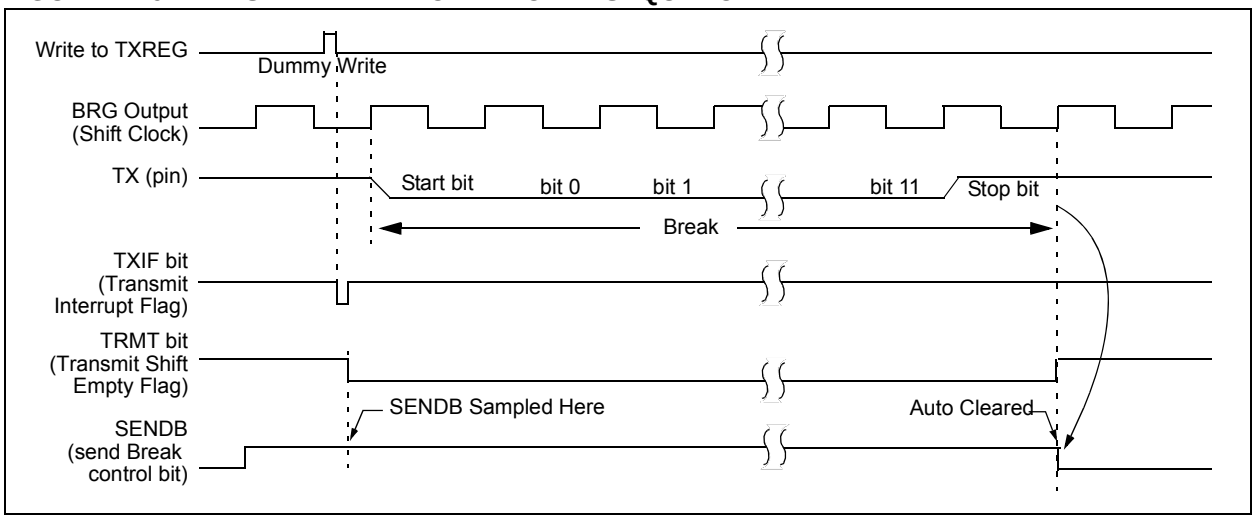


TABLE 25-2: SUPPLY VOLTAGE (I_{DD})(1,2) (CONTINUED)

PIC16LF1512/3			Standard Operating Conditions (unless otherwise stated)				
PIC16F1512/3							
Param No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D020		—	1.2	1.8	mA	3.0	F_{OSC} = 20 MHz HS Oscillator mode
		—	1.5	2.1	mA	3.6	
D020		—	1.4	1.7	mA	3.0	F_{OSC} = 20 MHz HS Oscillator mode
		—	1.7	2.3	mA	5.0	
D021		—	150	220	μA	1.8	F_{OSC} = 4 MHz EXTRC mode **(Note 3)**
		—	250	380	μA	3.0	
D021		—	200	330	μA	2.3	F_{OSC} = 4 MHz EXTRC mode **(Note 3)**
		—	280	420	μA	3.0	
		—	350	500	μA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through R_{EXT} is not included. The current through the resistor can be extended by the formula $I_R = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in kΩ.

TABLE 25-4: I/O PORTS (CONTINUED)

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
		Capacitive Loading Specs on Output Pins					
D101*	COSC2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1
D101A*	CIO	All I/O pins	—	—	50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

2: Negative current is defined as current sourced by the pin.

3: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

4: Including OSC2 in CLKOUT mode.

FIGURE 25-7: CLKOUT AND I/O TIMING

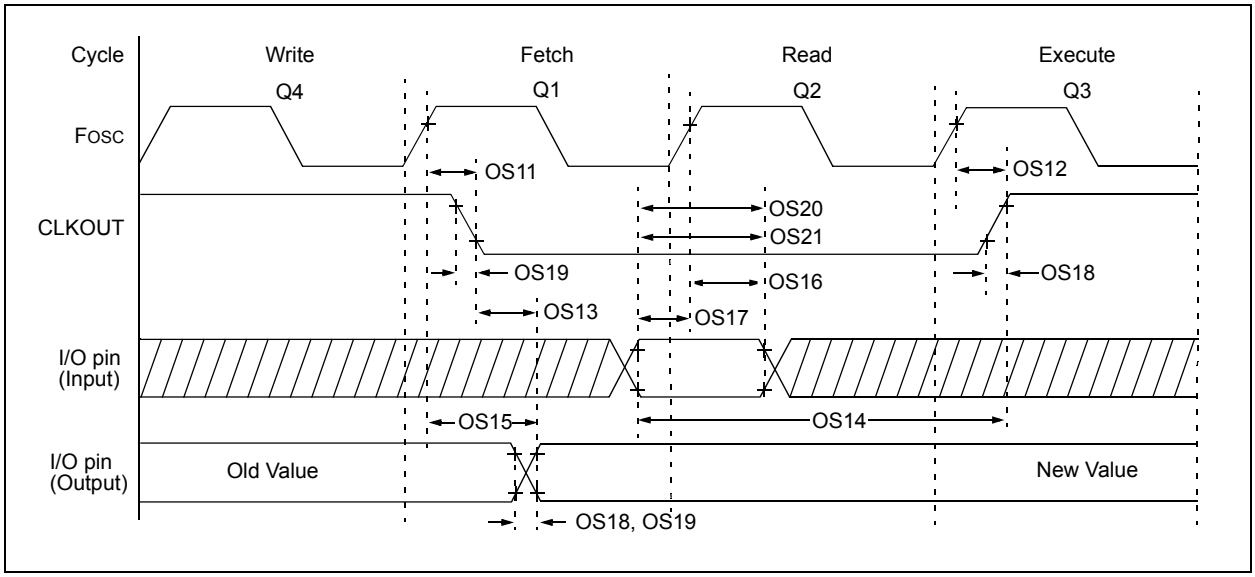


TABLE 25-8: CLKOUT AND I/O TIMING PARAMETERS

Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS11	TosH2ckL	FOSC↑ to CLKOUT↓ (1)	—	—	70	ns	VDD = 3.3-5.0V
OS12	TosH2ckH	FOSC↑ to CLKOUT↑ (1)	—	—	72	ns	VDD = 3.3-5.0V
OS13	TckL2ioV	CLKOUT↓ to Port out valid(1)	—	—	20	ns	
OS14	TioV2ckH	Port input valid before CLKOUT↑(1)	TOSC + 200 ns	—	—	ns	
OS15	TosH2ioV	Fosc↑ (Q1 cycle) to Port out valid	—	50	70*	ns	VDD = 3.3-5.0V
OS16	TosH2ioI	Fosc↑ (Q2 cycle) to Port input invalid (I/O in hold time)	50	—	—	ns	VDD = 3.3-5.0V
OS17	TioV2osH	Port input valid to Fosc↑ (Q2 cycle) (I/O in setup time)	20	—	—	ns	
OS18	TioR	Port output rise time	— —	40 15	72 32	ns	VDD = 1.8V VDD = 3.3-5.0V
OS19	TioF	Port output fall time	— —	28 15	55 30	ns	VDD = 1.8V VDD = 3.3-5.0V
OS20*	Tinp	INT pin input high or low time	25	—	—	ns	
OS21*	Tioc	Interrupt-on-change new input level time	25	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

TABLE 25-13: A/D CONVERSION REQUIREMENTS

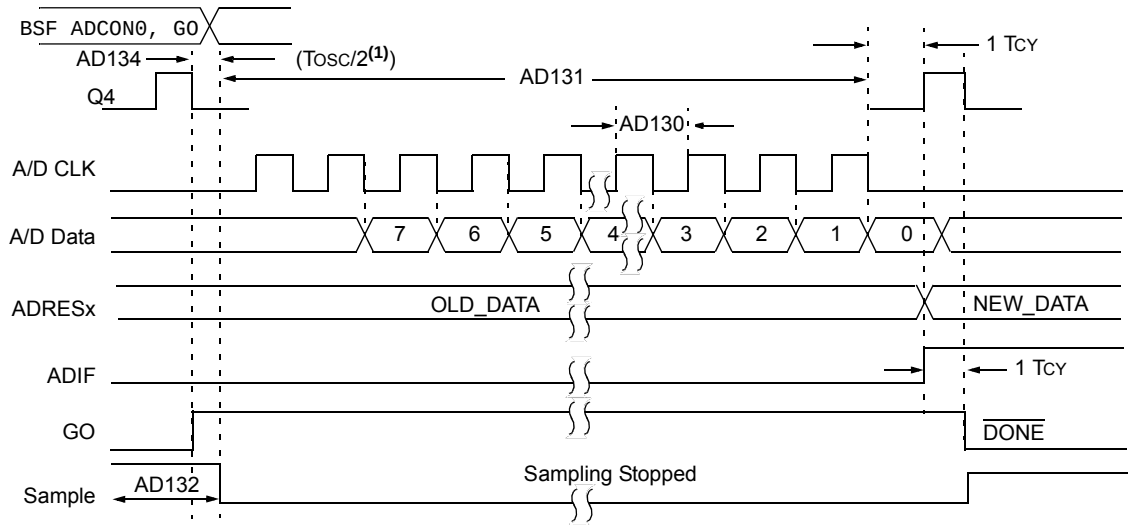
Standard Operating Conditions (unless otherwise stated)							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD130*	TAD	A/D Clock Period	1.0	—	9.0	µs	TOSC-based
		A/D Internal RC Oscillator Period	1.0	1.6	6.0	µs	ADCS<1:0> = 11 (ADRC mode)
AD131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	11	—	TAD	Set GO/$\overline{\text{DONE}}$ bit to conversion complete
AD132*	TACQ	Acquisition Time	—	5.0	—	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The ADRES register may be read on the following TCY cycle.

FIGURE 25-12: A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 26-27: IDD TYPICAL, HS OSCILLATOR, PIC16LF1512/3 ONLY

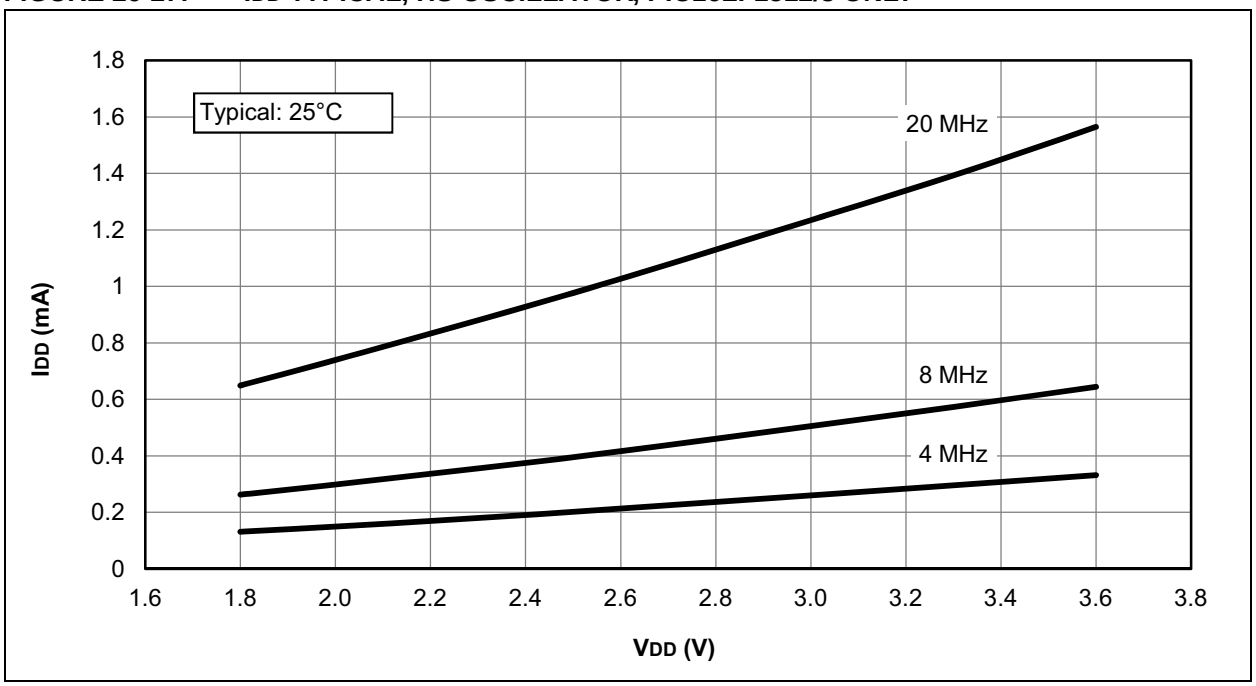
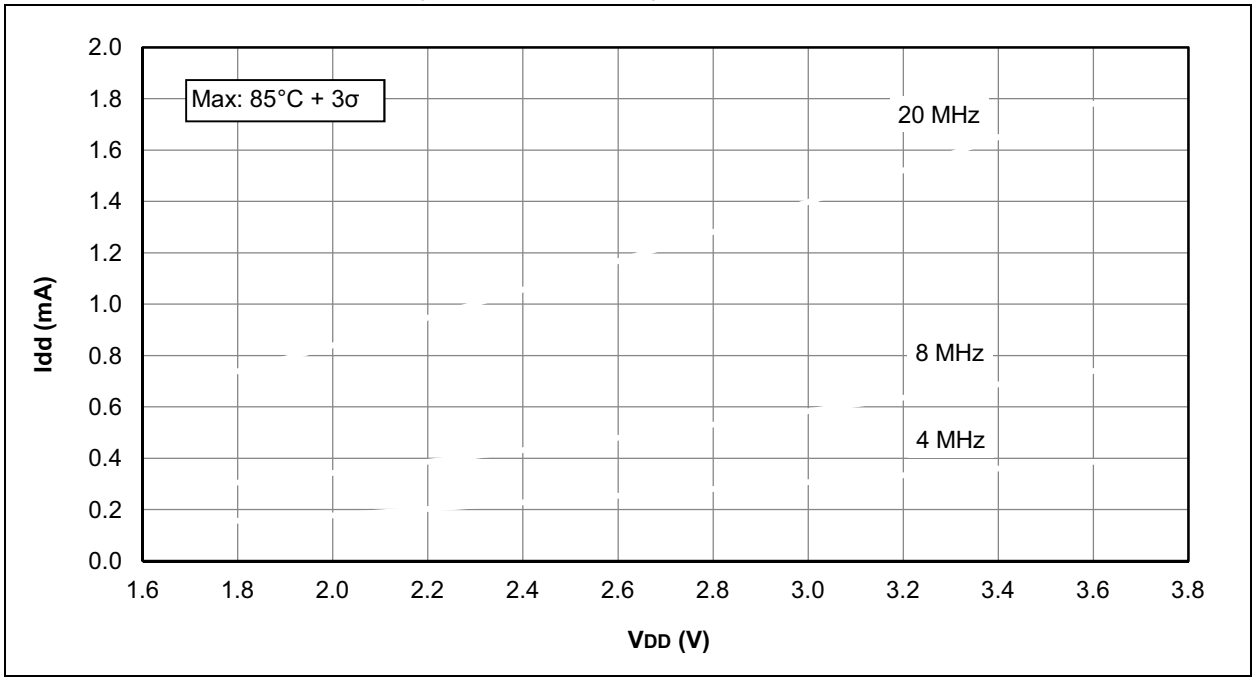
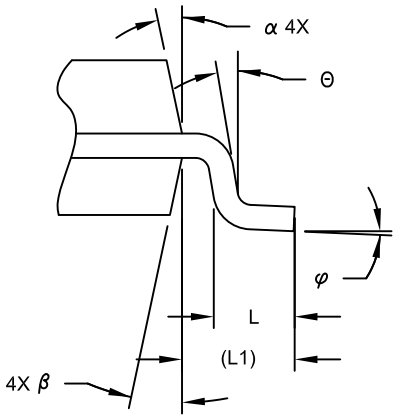


FIGURE 26-28: IDD MAXIMUM, HS OSCILLATOR, PIC16LF1512/3 ONLY

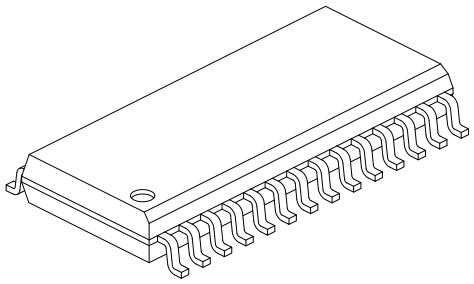


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2